

Power Electronics Packaging – Training and Upskilling
University of Nottingham – Wednesday 23 November 2022

Highlights:

- *Assessment of Power Electronics Packaging Options*
- *Selection of Devices*
- *Discrete Device*
- *Chip on Substrate*
- *Wafer Level Packaging*
- *Selection of Substrates*
- *Integrated Power Modules*
- *Opportunity for Q&A*

Registration:

	<i>Delegates</i>
<i>IMAPS Members</i>	100
<i>Students (under and post graduates)</i>	50
<i>Non Member</i>	160
<i>Attendees at IPower4 Conference receive a £30 discount</i>	
<i>Prices - £ exclude VAT, including lunch and refreshments</i>	

Register Here

A Half-Day Training Workshop on the Developing Power Electronics Packaging Options

IMAPS-UK is organising a half-day **Power Electronics Packaging Training Workshop** to provide a more thorough understanding of the available **Power Electronics Packaging Options** involved in the assembly of power electronics components and modules that will form the basis of the Electric Revolution.

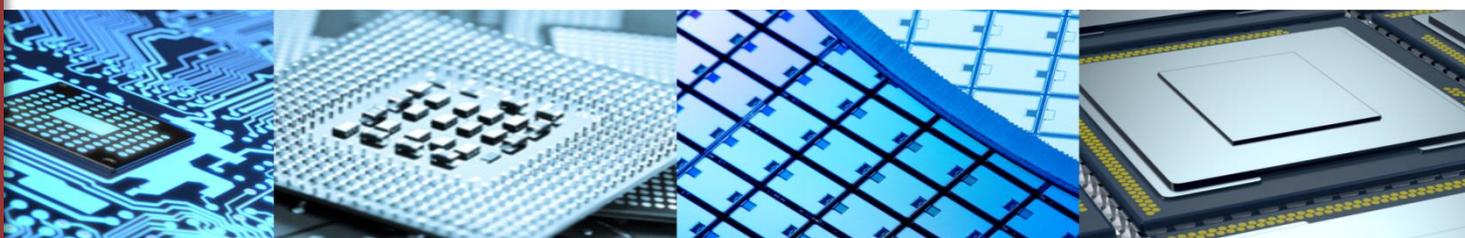
One of the most significant challenges will be the achievement of reliable and fully functional products that will require electronic and electrical packaging solutions that can operate at higher currents and voltages, faster frequencies and increased temperatures, which will place increasingly severe demands on the materials and assembly processes.

This workshop will focus on the following aspects of assessing Power Electronics Packaging Options, including:

- **Selection of Devices**
- **Discrete Devices/Chip on Substrate/Wafer Level Packaging**
- **Selection of Substrates**
- **Integrated Power Modules**

The workshop will address the training needs of students and researchers within Colleges and Universities and personnel within industrial companies to assist in the upskilling and reskilling of people for the design, manufacture and testing of power modules. Attendees can receive a Certificate of Attendance that can be used as proof of Continuous Professional Development.

The setting up of this Workshop has been supported by Innovate UK Project “Power Electronics Packaging – Training and Upskilling” and funded by the Driving the Electric Revolution, an ISCF Challenge delivered by UK Research and Innovation.



Course Agenda:

Wednesday 23 November 2022

- 12:00 – Welcome, Lunch and Networking
- 12:30 – Introduction to PEPTUS and Power Devices
- 13:20 - Break
- 13:30 – Packaging Power Devices
- 14:20 - Break
- 14:30 – Selection of Substrates
- 15:20 – Break, Refreshments and Networking
- 15:50 – Integrated Power Modules
- 16:40 – Q&A and Discussion
- 17:00 - Close

[Register Here](#)

The Venue

**De Vere Jubilee Conference Centre
Triumph Road
Nottingham
NG7 2TU
www.nottinghamvenues.com**

For further details, please contact the IMAPS-UK Office.

e-mail: office@imaps.org.uk,
T: 44 (0) 131 202 9004



Course Module Level

This course is classified as **Intermediate Level** (see below)

Who should attend:

- Engineers and Technicians involved in Power Electronics Design, Manufacture and Test
- Undergraduates and Post-graduates interested in Power Electronics Research and Development
- Engineers and Technicians seeking to become involved in Driving the Electric Revolution
- QC/Reliability Personnel and Managers wanting to gain an appreciation of power electronics assembly processes

Access to Course Presentations:

Attendance at the Course includes downloadable access to the presentation content.

Your Workshop Tutors:

Andy Longford is founder and managing Partner of technical consulting company **PandA Europe**. He has been working in the Semiconductor Packaging and Assembly industry for over 30 years. He has authored over 30 technical papers on Electronics Interconnect, Chip Packaging and Lead-Free electronics developments. He has served on a number of UK Government technical committees, he is an EPSRC College peer review member, a registered EU Research Project evaluator, a committee member of IMAPS-UK and a member of the SEMI Europe Advanced Packaging Committee.

Steve Riches is co-director of **Tribus-D** and has over 30 years experience in electronics assembly innovation. Technical developments have included copper wire bonding, high temperature and power electronics

The PEPTUS Training and Upskilling Project on Power Electronics Packaging

IMAPS-UK has prepared a Power Electronics Packaging Training Course based on Basic, Intermediate and Advanced levels to address the needs from introduction to power electronics packaging for schools/colleges and Universities through to detailed training to assist in upskilling and reskilling personnel for the manufacture and testing of power modules.

Basic: Raising awareness of power electronics packaging explaining the fundamentals and significance of power electronics packaging in the drive towards electrification.

Intermediate: Enabling interested parties to gain understanding of the details of power electronics packaging for those needing re-skilling from adjacent industries or who are already working in the field of power electronics.

Advanced: Assisting participants in the implementation of power electronics packaging in Research and Development, prototyping and manufacturing.